

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT



In re application of:)	Examiner: To be assigned
Bhatt et al.)	
)	
Serial No. To be assigned)	Art Unit:
)	
Filed: Herewith)	
)	
For: Full Additive Process with Filled Plated Through Holes)	
)	

Attorney Docket No. END919960141US2 (IEN-10-5222-D1)

PRELIMINARY AMENDMENT

Box Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Applicants are herewith filing a divisional application of application Serial No. 09/047,984, filed on March 25, 1998. Applicants hereby elect claims 9-11 of the previous application. It is respectfully requested that this application be amended as follows:

In the specification:

Kindly amend the specification as follows:

Page 1, first paragraph, after "**Related Applications**", add the following sentence:

--This application is a divisional of application Serial No. 09/047,984, filed March 25, 1998.--

IN THE CLAIMS:

Please cancel claims 1-8 of the prior application.

Please add the following new claims:

12. (new) The invention as defined in claim 9 wherein said circuitry includes a pad on each of said filled plated through holes.
13. (new) The invention as defined in claim 10 wherein said circuitry includes a pad on each of said filled plated through holes.
14. (new) The invention as defined in claim 11 wherein said circuitry includes a pad on each of said filled plated through holes.
15. (new) The invention as defined in claim 9 further characterized by a layer of dielectric material disposed on said dielectric substrate and overlying said circuitry on said dielectric substrate, said layer of dielectric material having at least one via formed therein.
16. (new) The invention as defined in claim 10 further characterized by a layer of dielectric material disposed on said dielectric substrate and overlying said circuitry on said dielectric substrate, said layer of dielectric material having at least one via formed therein.

17. (new) The invention as defined in claim 11 further characterized by a layer of dielectric material disposed on said dielectric substrate and overlying said circuitry on said dielectric substrate, said layer of dielectric material having at least one via formed therein.

18. (new) The invention as defined in claim 15 further characterized by circuitry disposed on said layer of dielectric material.

19. (new) The invention as defined in claim 16 further characterized by circuitry disposed on said layer of dielectric material.

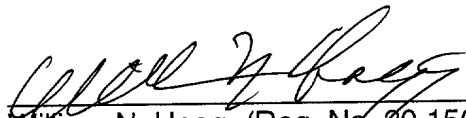
20. (new) The invention as defined in claim 17 further characterized by circuitry disposed on said layer of dielectric material.

REMARKS

The new claims do not constitute new matter since they find support in the specification on page 10, line 29, through page 11, line 30.

Respectfully submitted,

Date: 2-7-01


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